

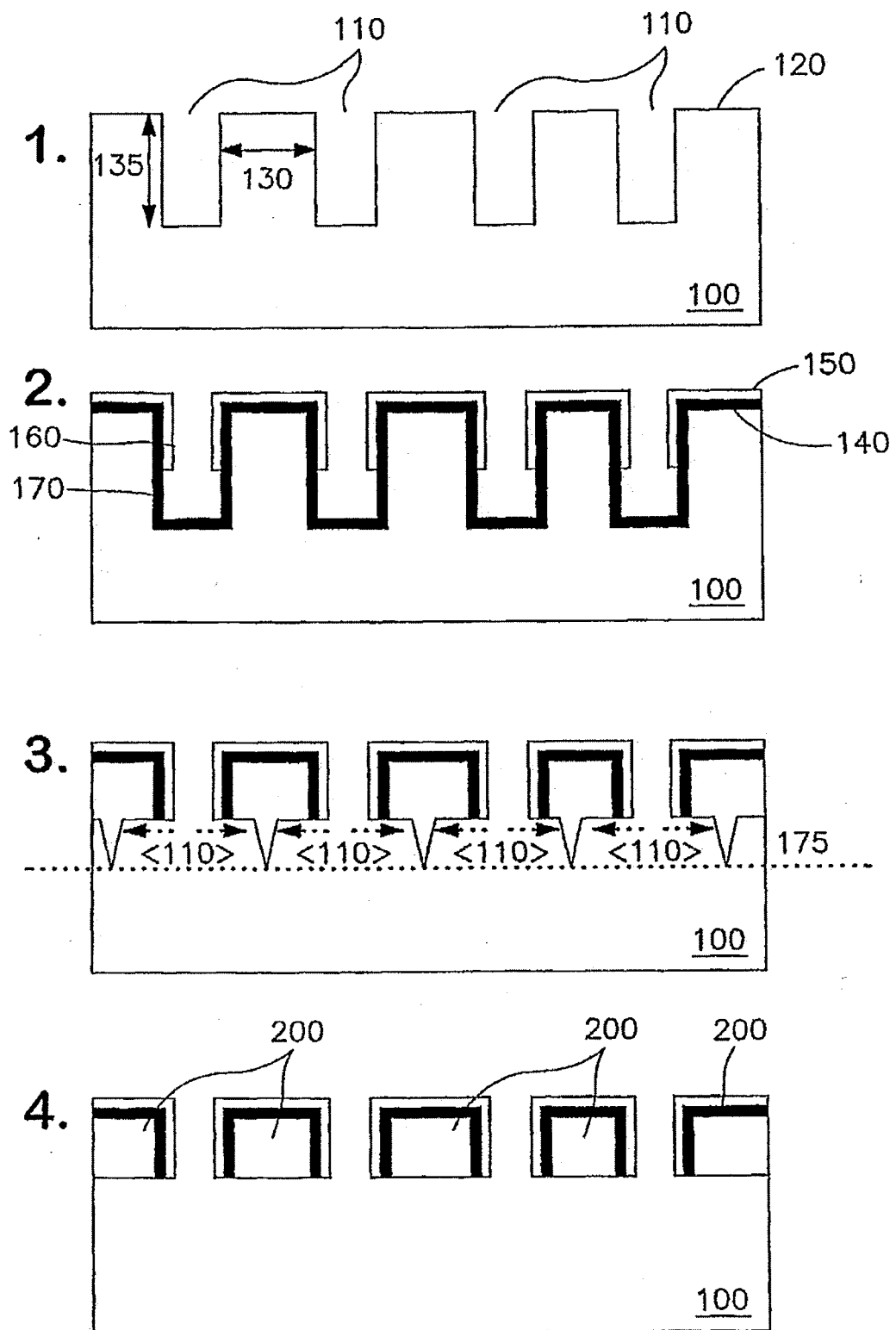


FIG. 1a

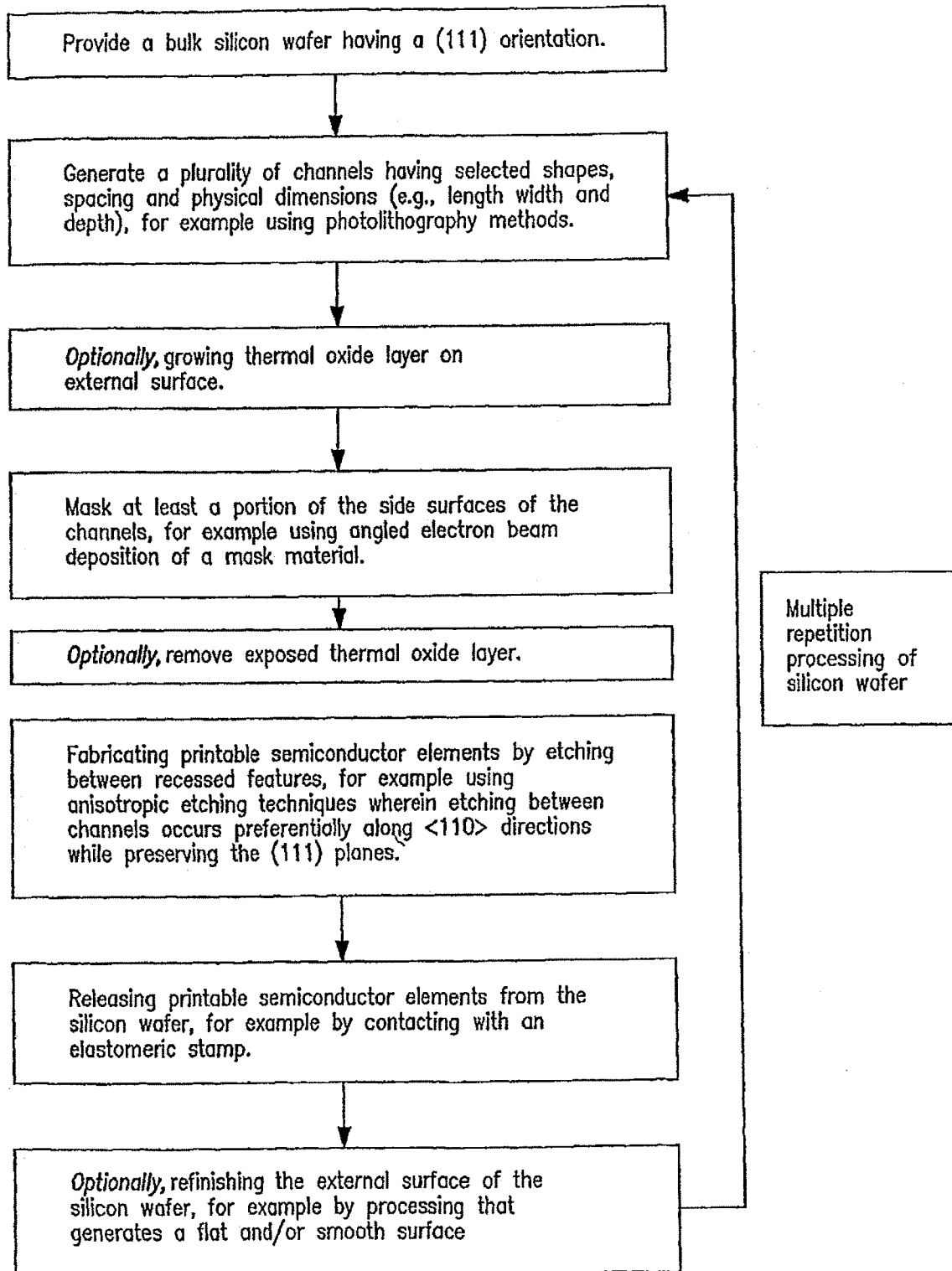


FIG. 1b

FIG. 1c



Anisotropic etching of unmasked regions;  
generation of free-standing structures

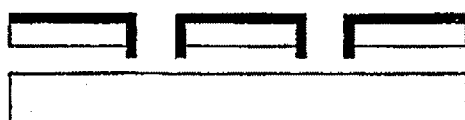


FIG. 1d

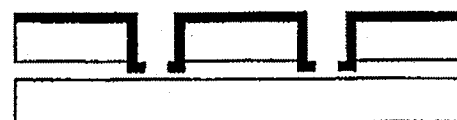
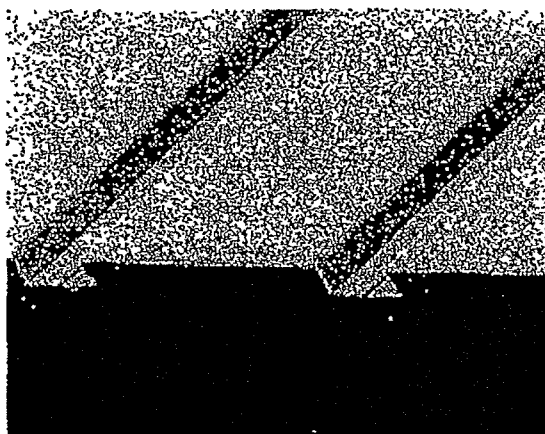


FIG. 1e



FIG. 1f



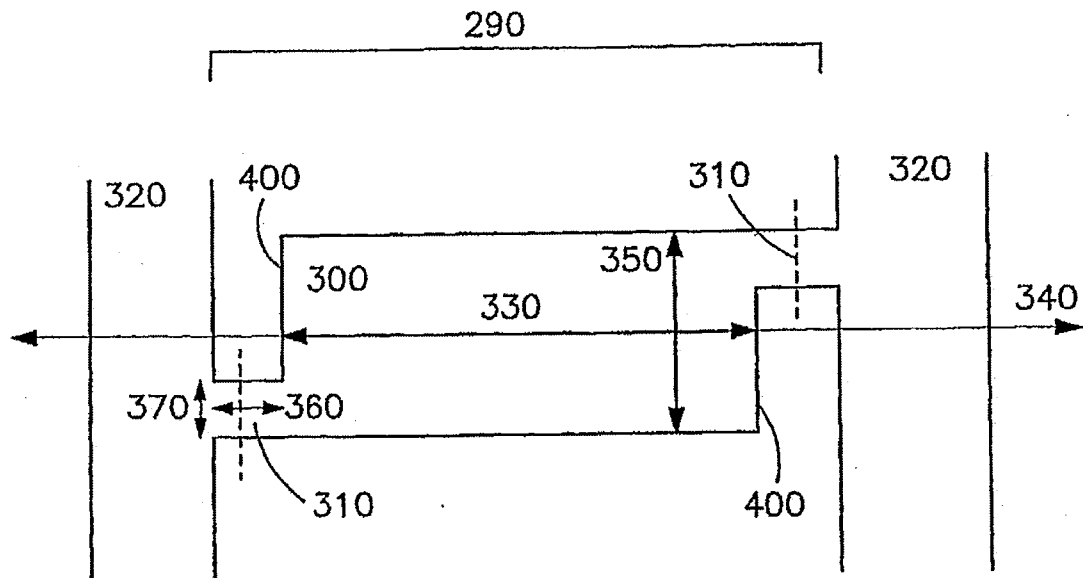


FIG. 2a

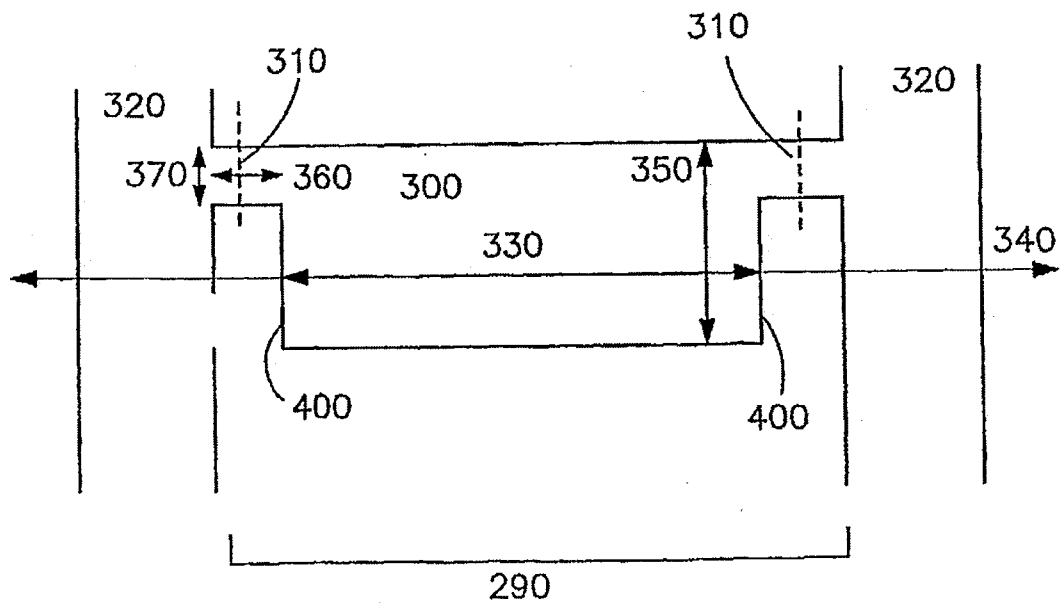


FIG. 2b

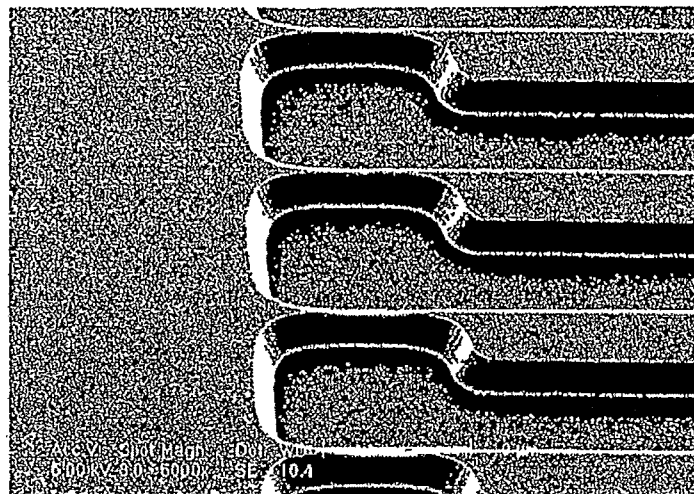


FIG. 2c

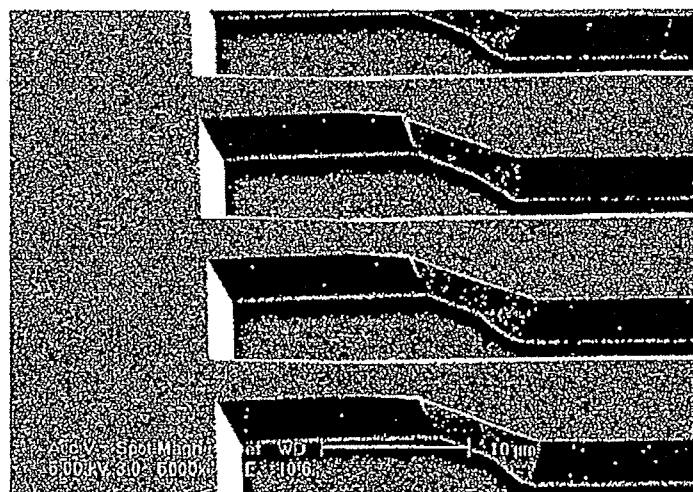


FIG. 2d

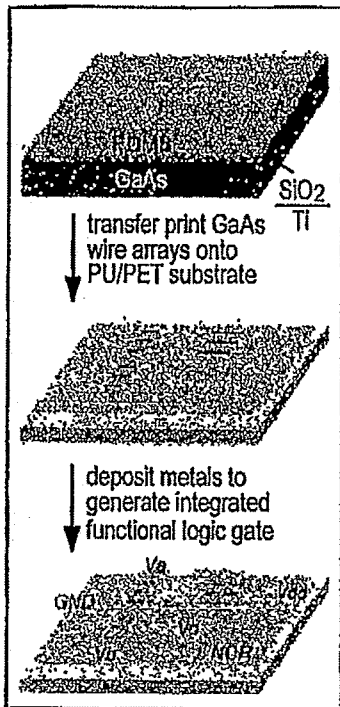


FIG. 3a

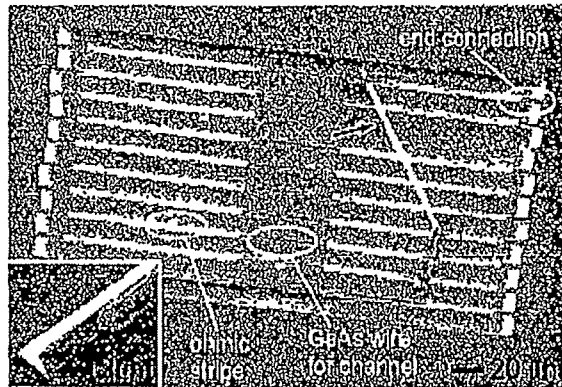


FIG. 3b

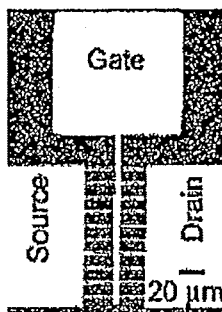


FIG. 3c

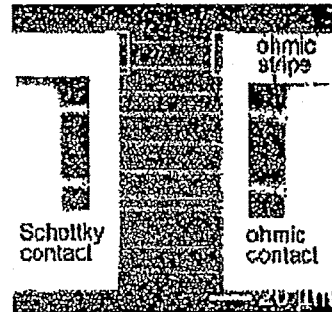


FIG. 3d

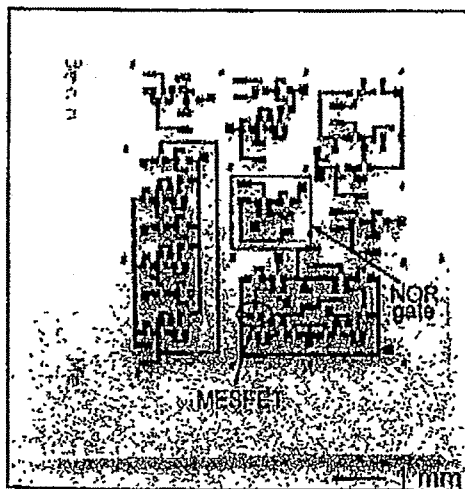


FIG. 3e

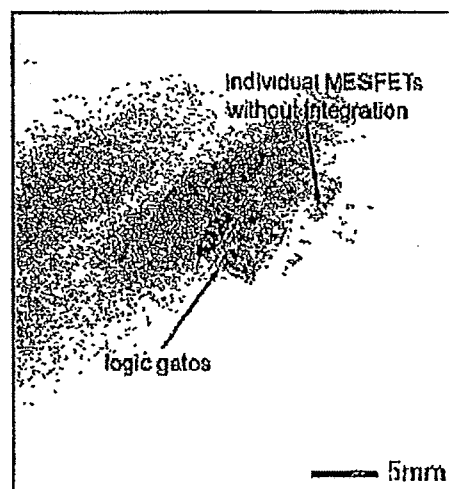


FIG. 3f

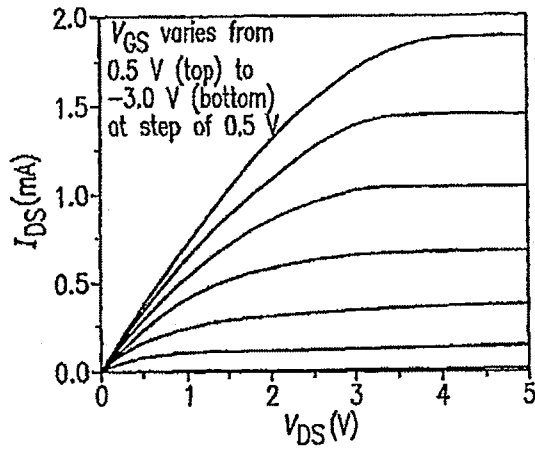


FIG. 4a

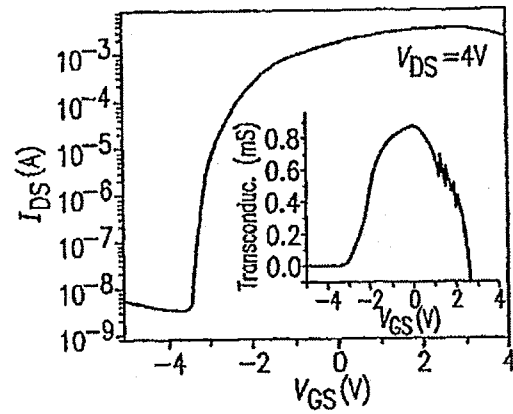


FIG. 4b

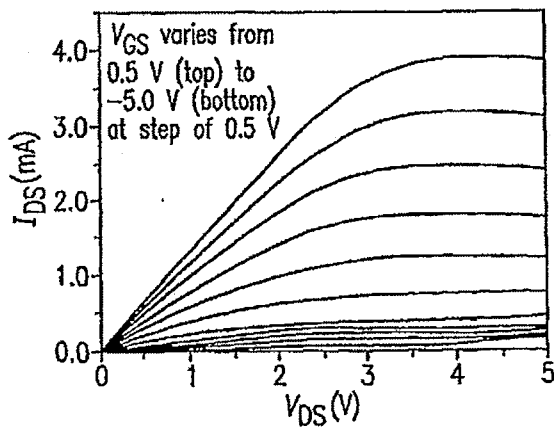


FIG. 4c

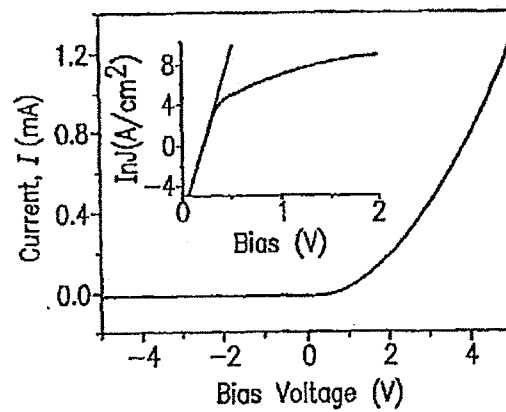


FIG. 4d

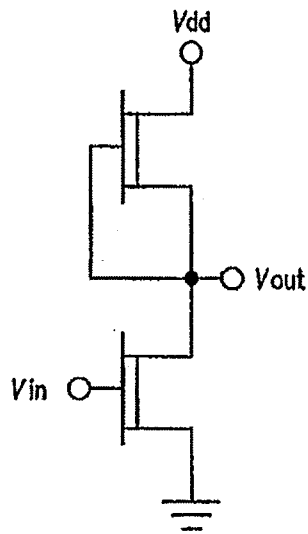


FIG. 5a



FIG. 5b

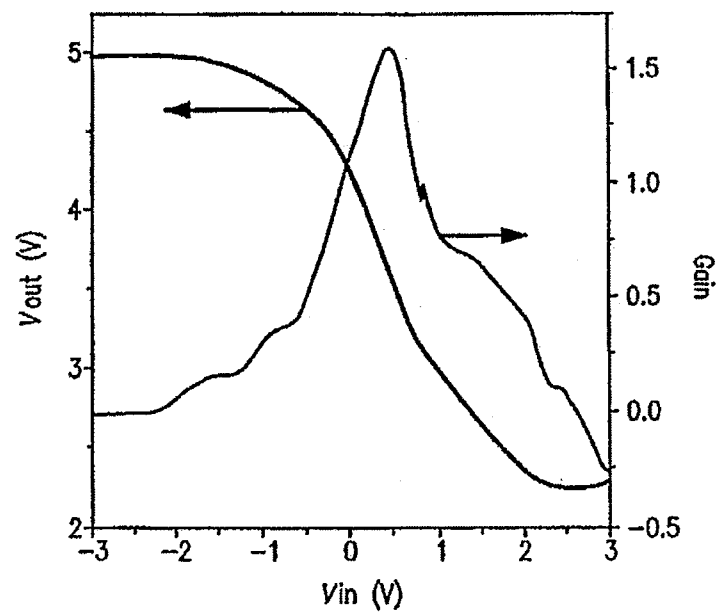


FIG. 5c

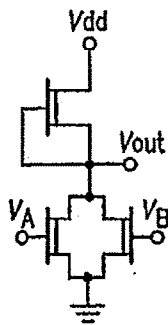


FIG. 6a



FIG. 6b

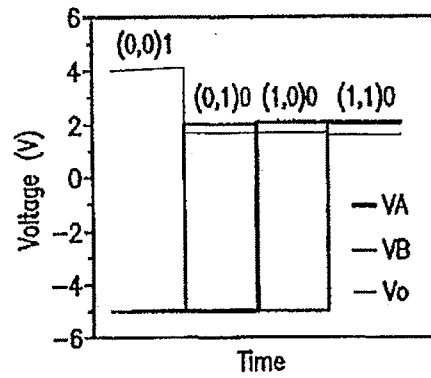


FIG. 6c

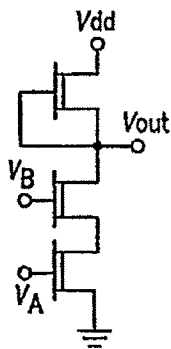


FIG. 6d

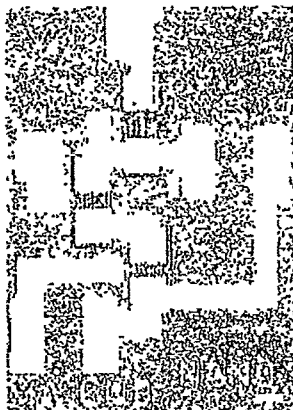


FIG. 6e

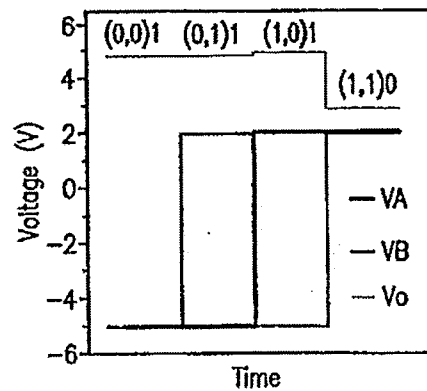


FIG. 6f

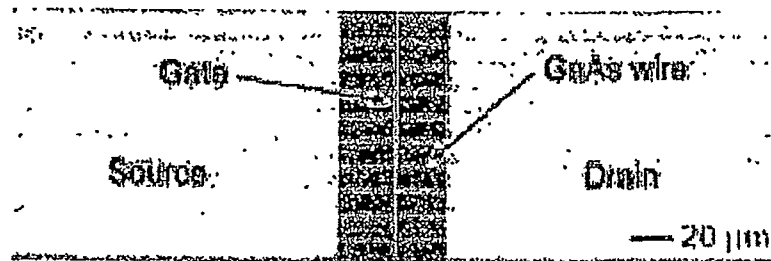


FIG. 7a

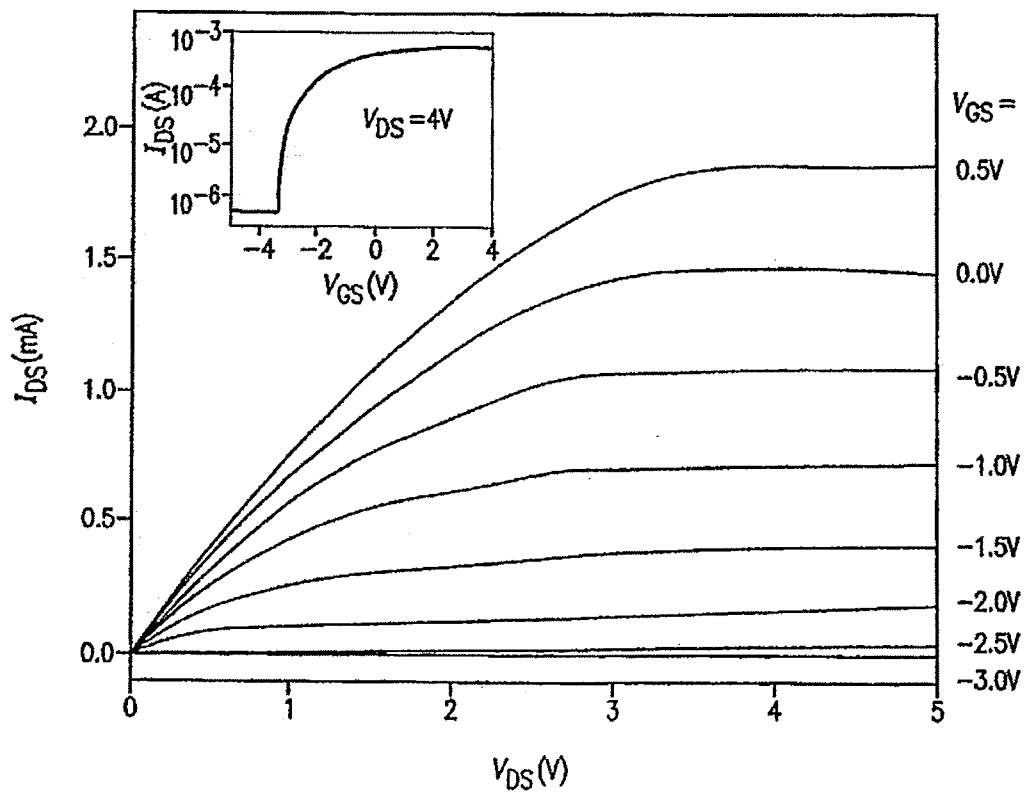


FIG. 7b

FIG. 8a

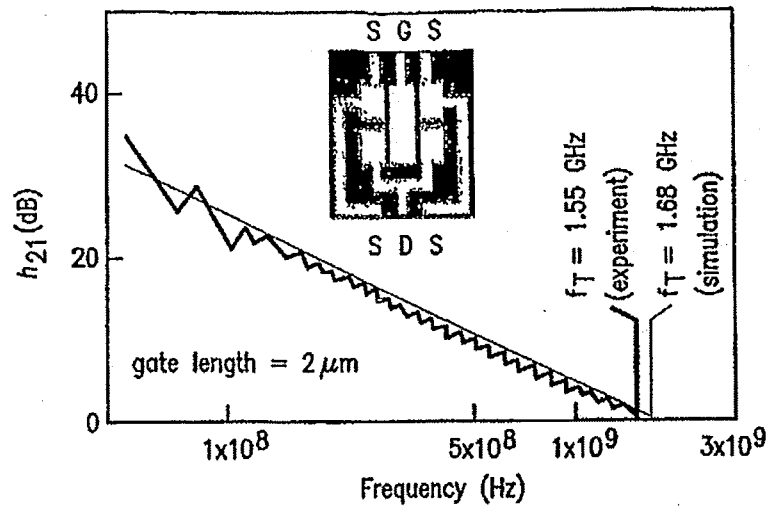


FIG. 8b

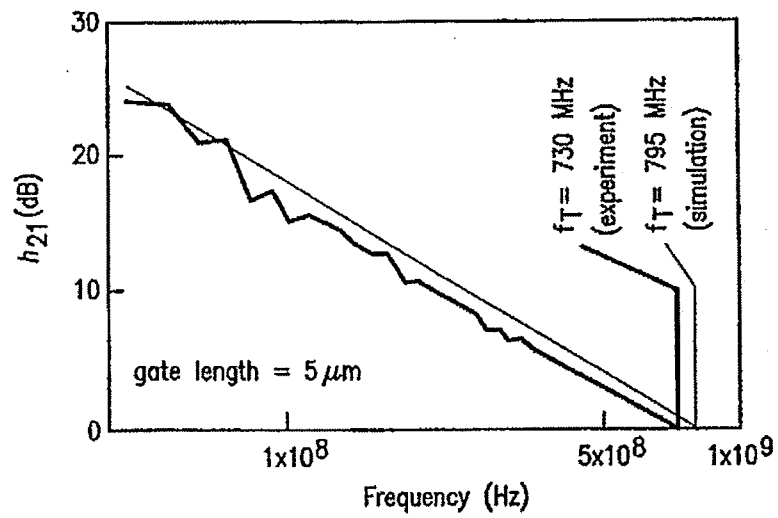


FIG. 8c

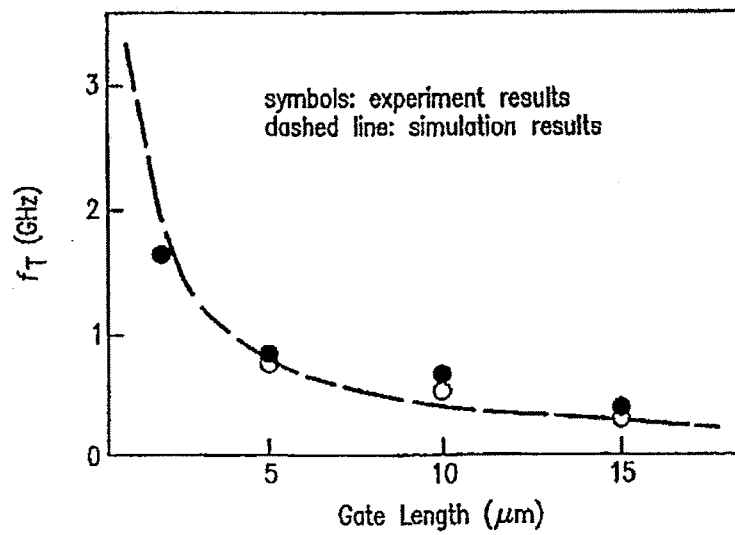


FIG. 9a

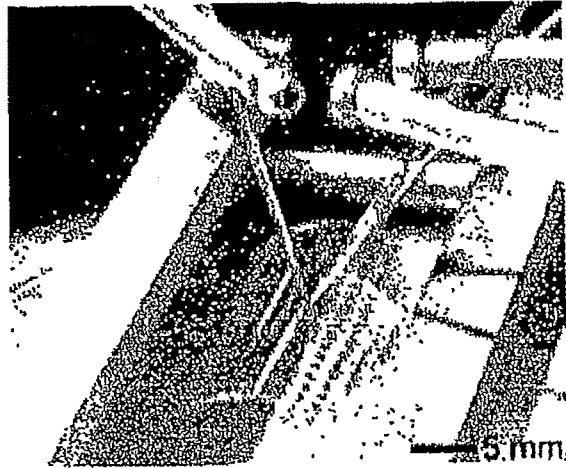


FIG. 9b

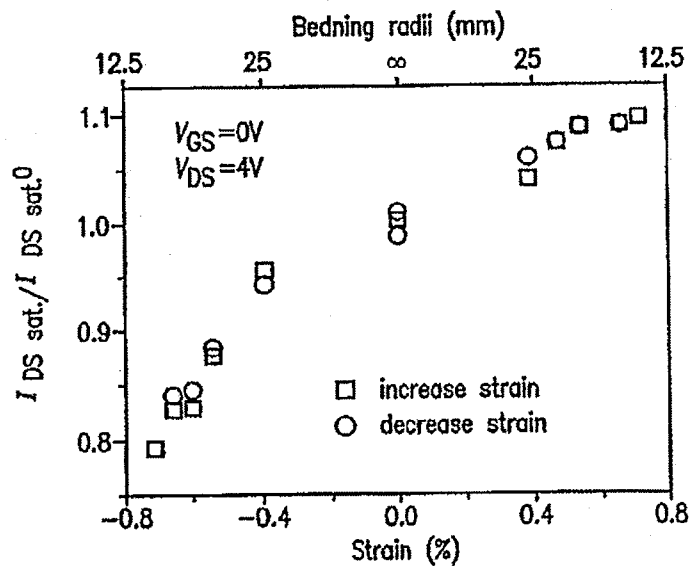
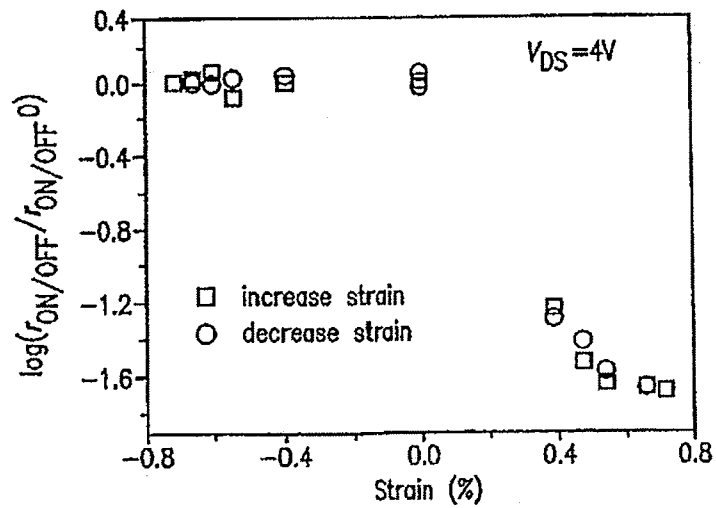
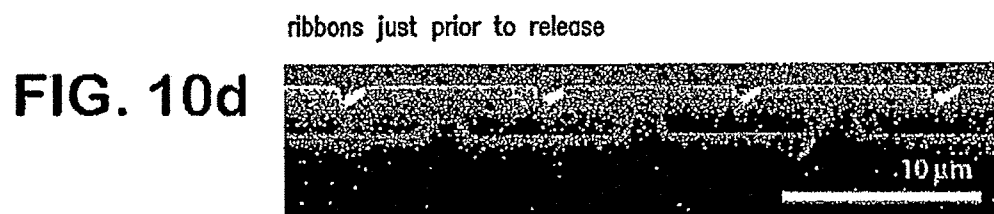
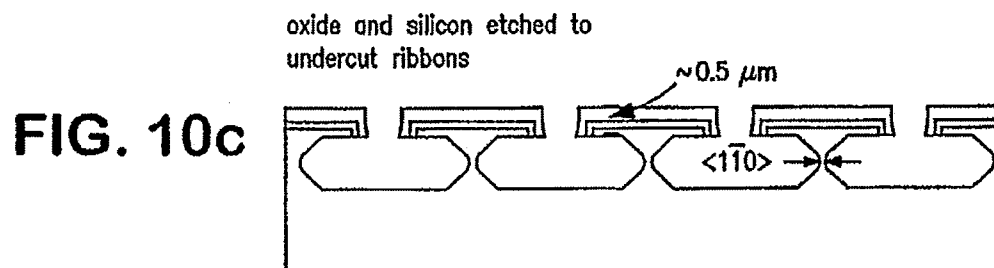
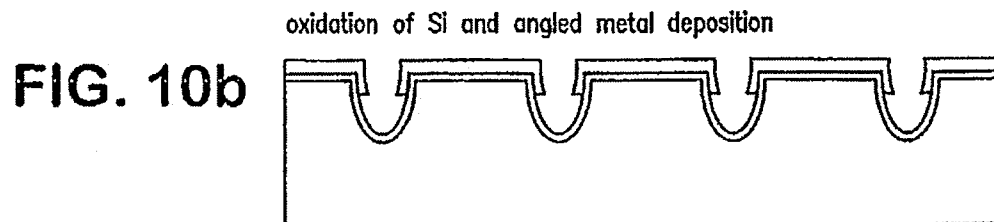
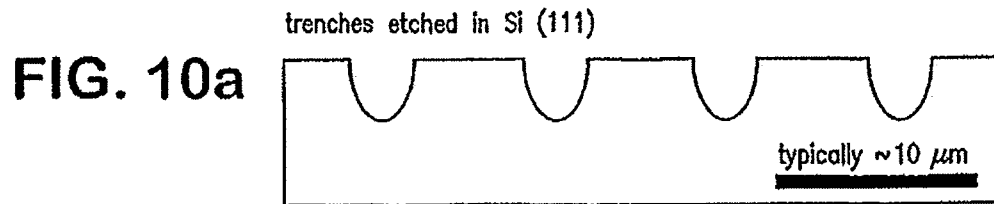
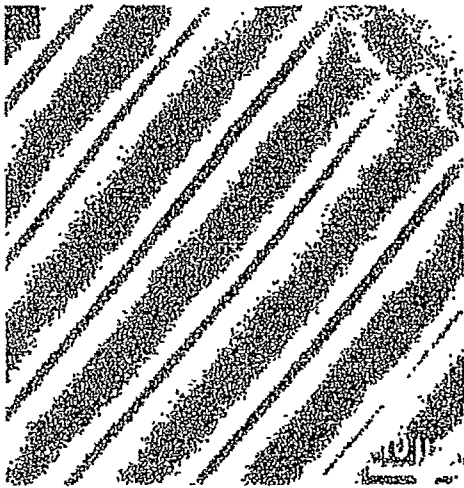


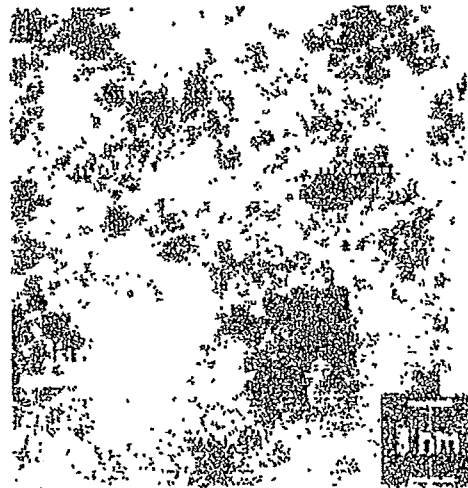
FIG. 9c







**FIG. 11a**



**FIG. 11b**

apply stamp to  
donor substrate

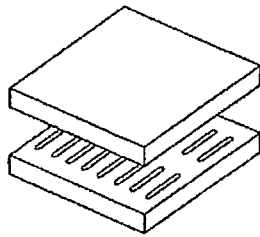


FIG. 12a

retrieve ribbons

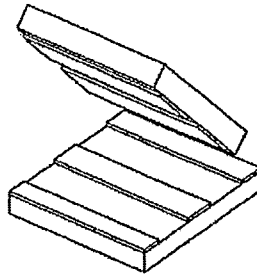


FIG. 12b

print ribbons onto  
plastic sheet

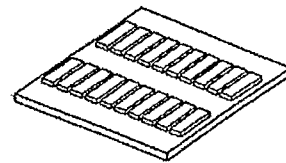


FIG. 12c



FIG. 12d

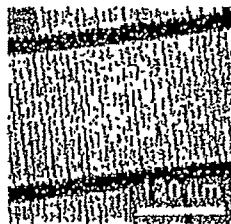


FIG. 12e



FIG. 12f

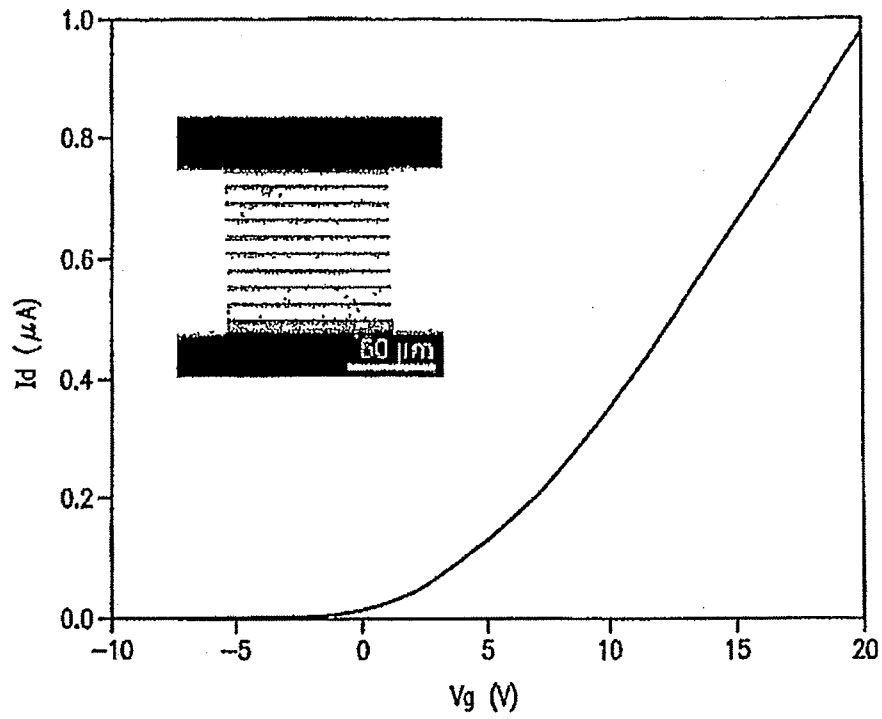


FIG. 13a

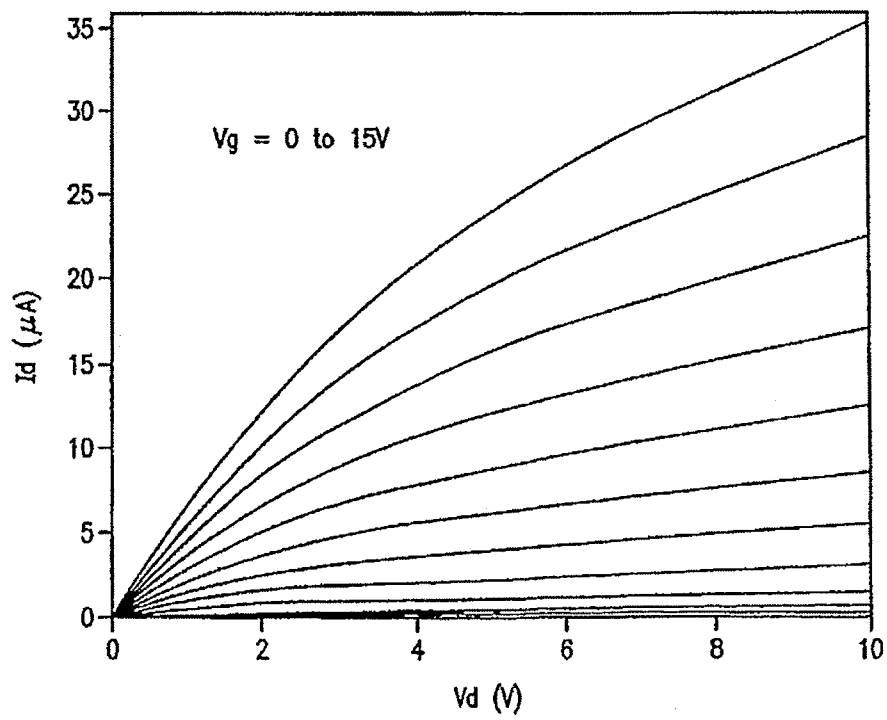


FIG. 13b

FIG. 14a

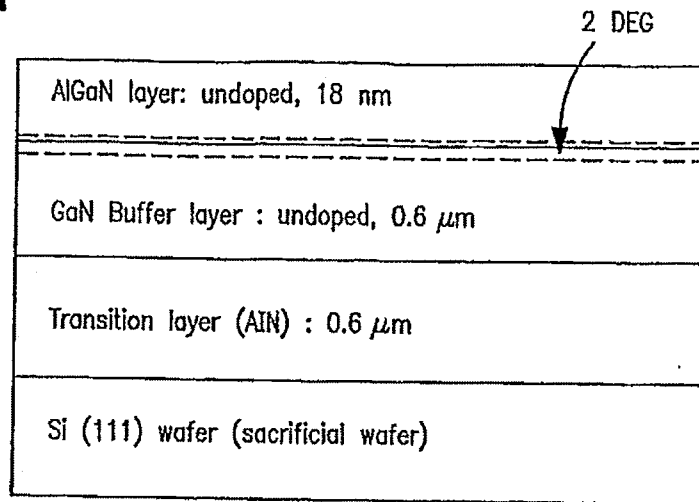


FIG. 14b

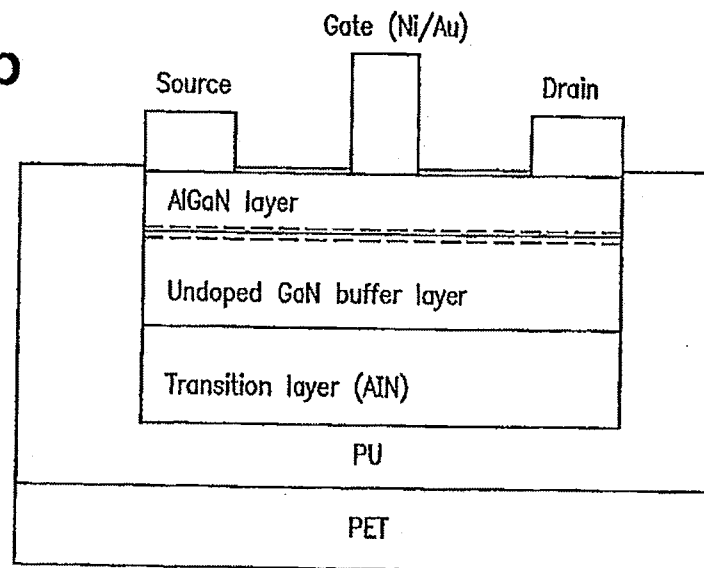
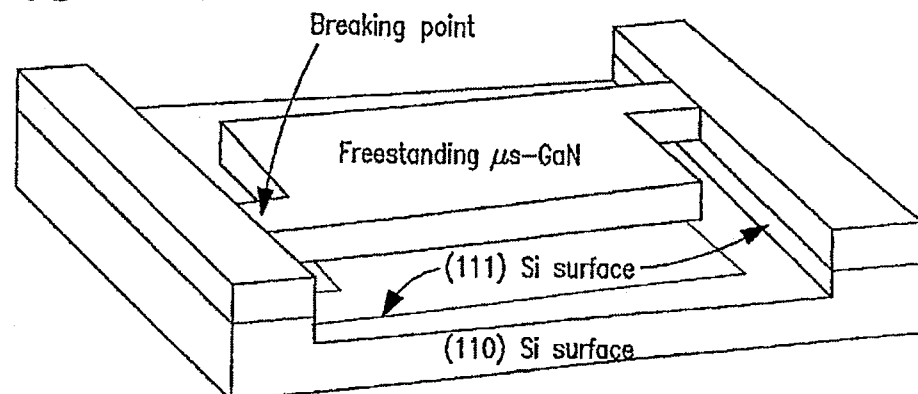
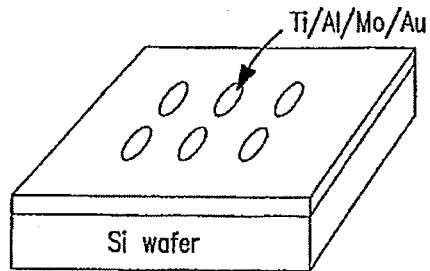


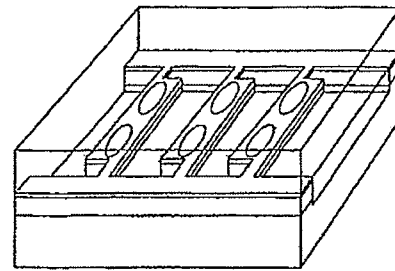
FIG. 14c



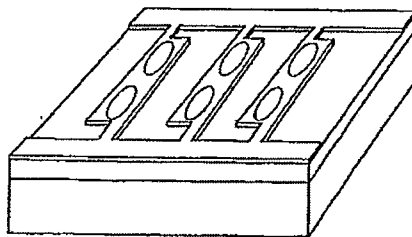
Ohmic contact on GaN stack

**FIG. 15a**

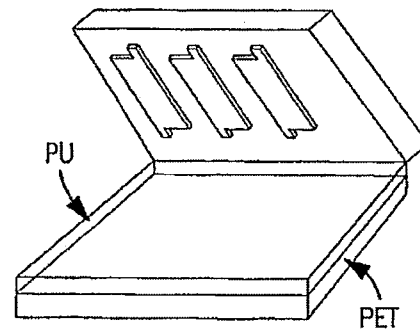
Transfer to PDMS

**FIG. 15e**

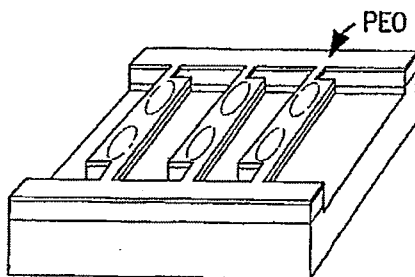
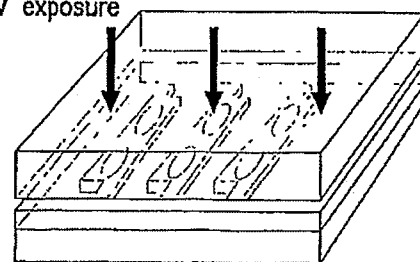
Ribbon pattern with PEO/Cr

**FIG. 15b**

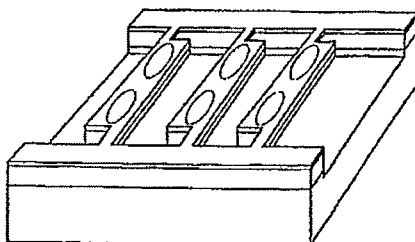
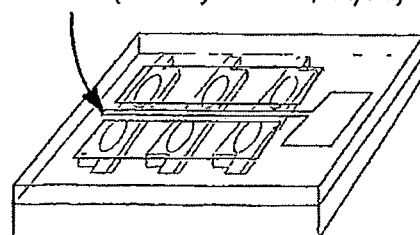
Spincast PU on plastic

**FIG. 15f**

ICP etching of GaN

**FIG. 15c**Contact PDMS to PET  
UV exposure**FIG. 15g**

TMAH etching of underlying Si

**FIG. 15d**Removing oxide & metal contact  
Gate (Schottky contact, Ni/Au)**FIG. 15h**

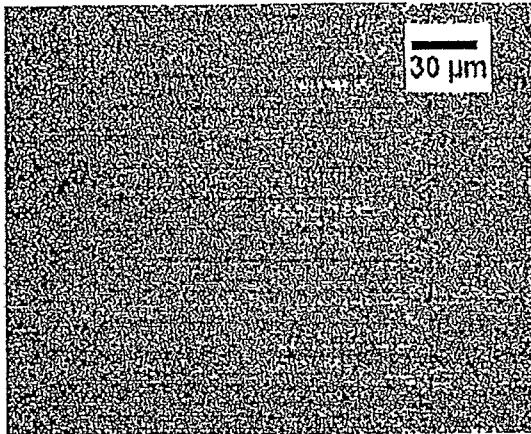


FIG. 16a

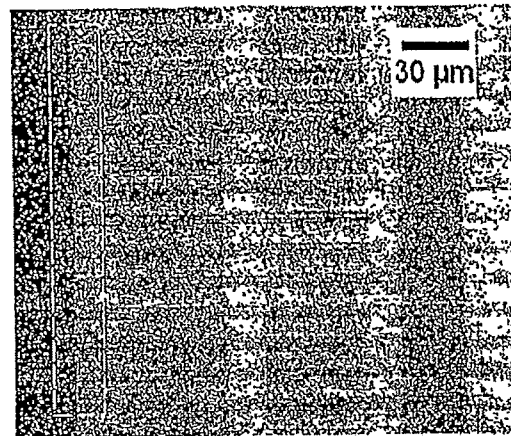


FIG. 16b

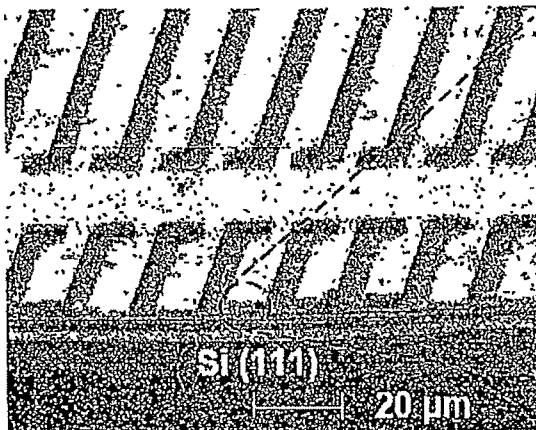


FIG. 16c

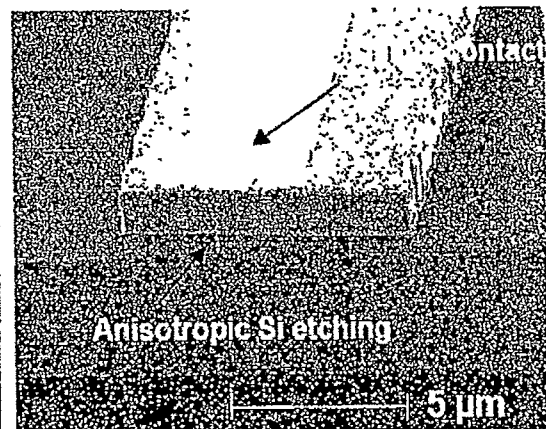


FIG. 16d



FIG. 16e

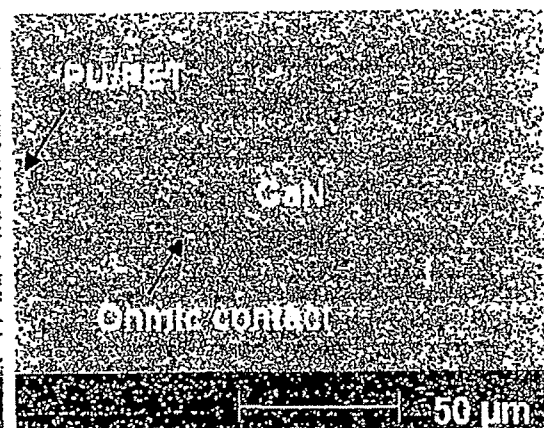


FIG. 16f

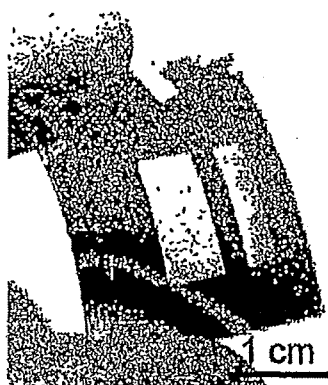


FIG. 17a

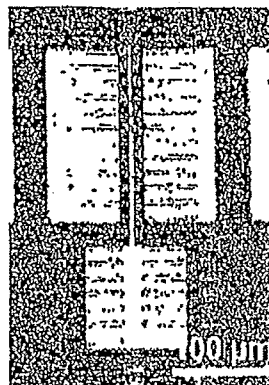


FIG. 17b

FIG. 17c

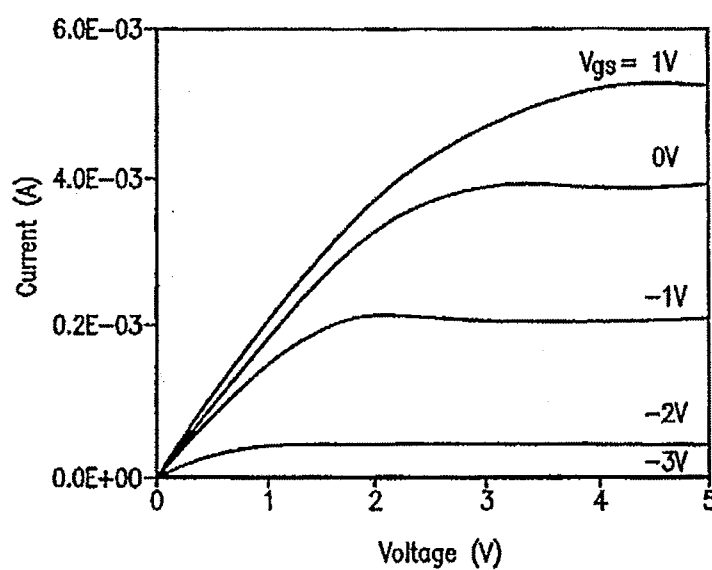


FIG. 17d

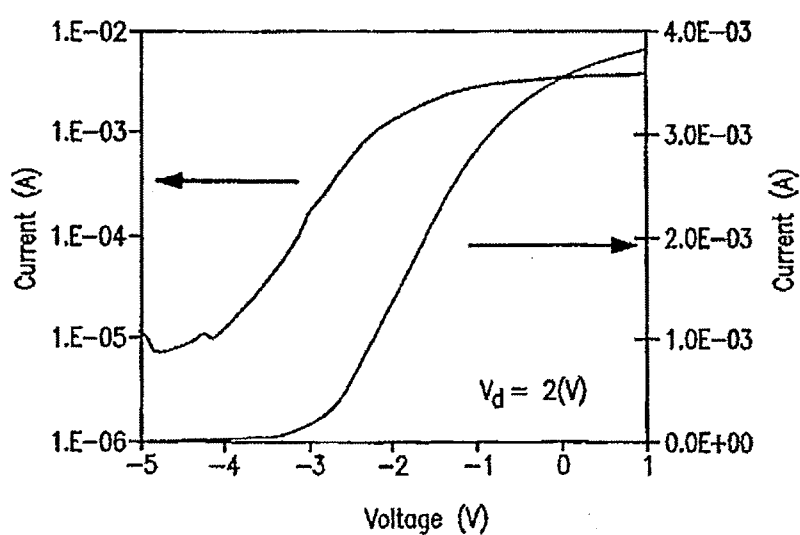


FIG. 18a

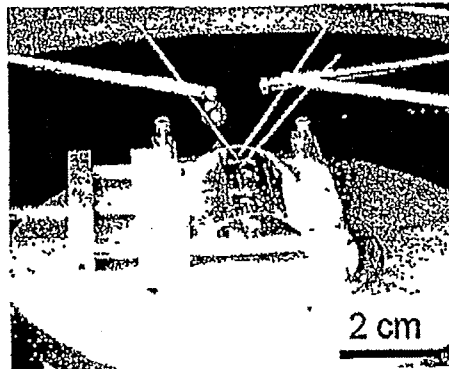


FIG. 18b

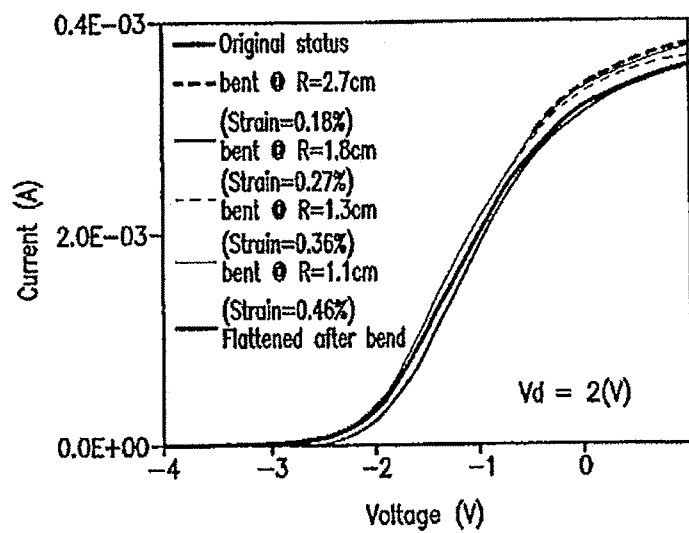
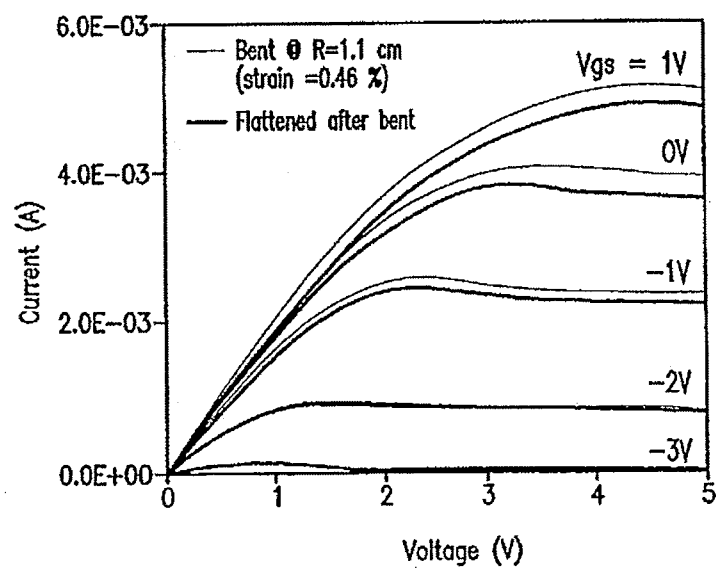


FIG. 18c



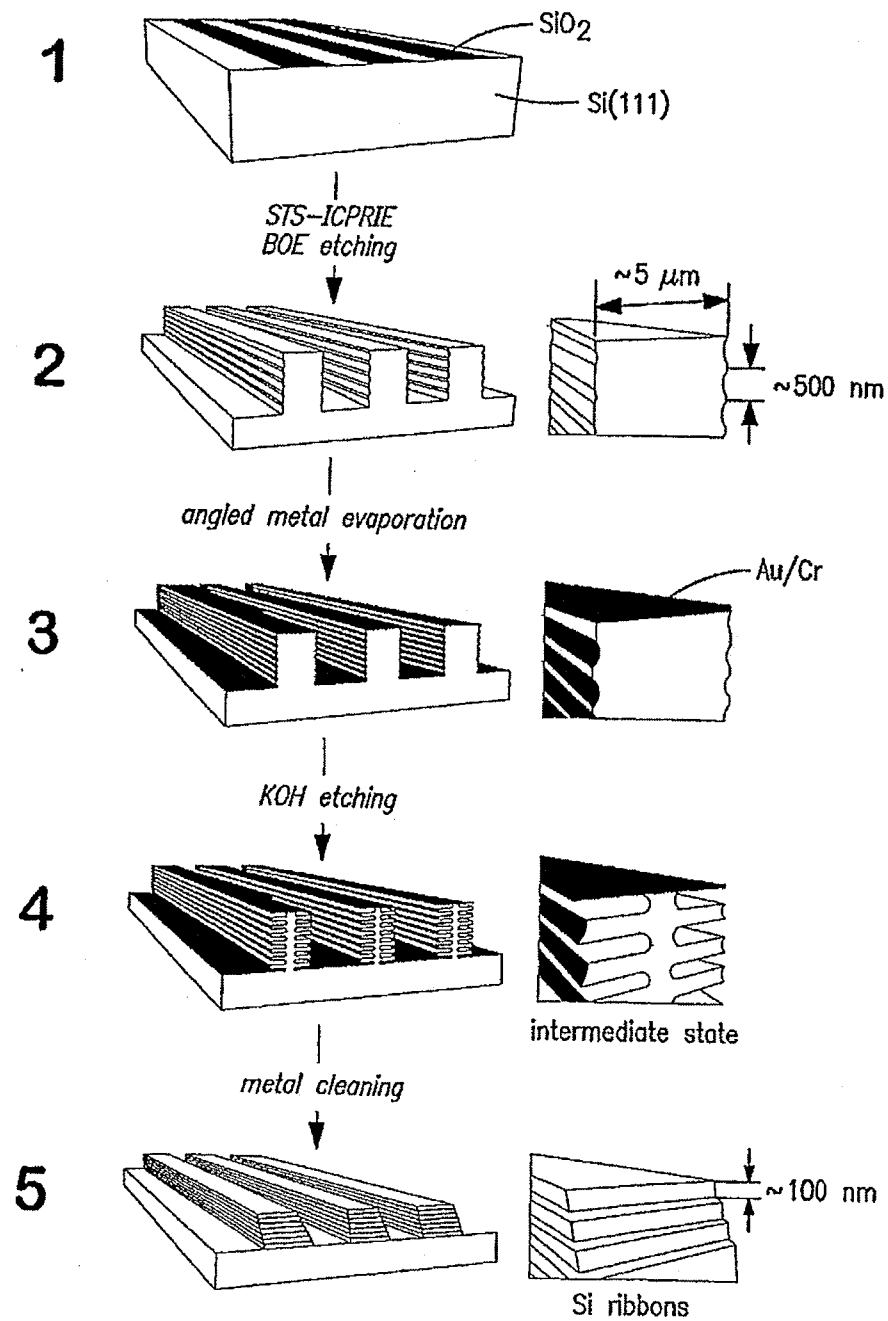


FIG. 19

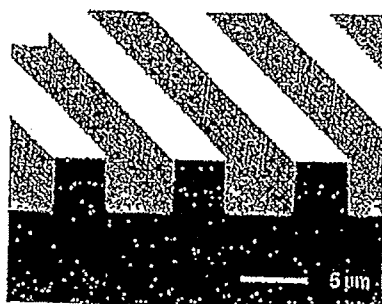


FIG. 20a

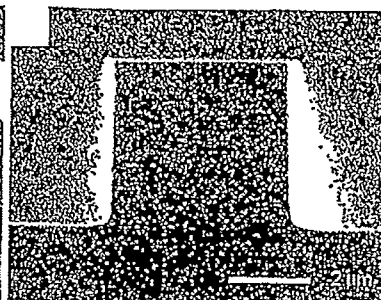


FIG. 20b

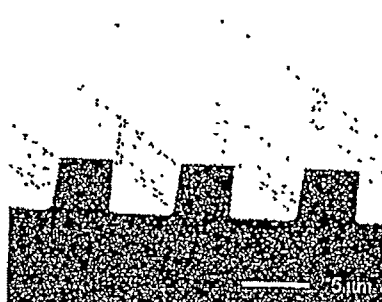


FIG. 20c

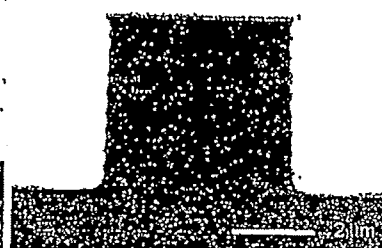


FIG. 20d

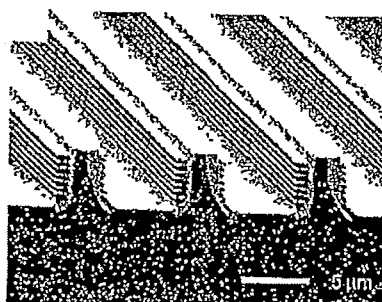


FIG. 20e

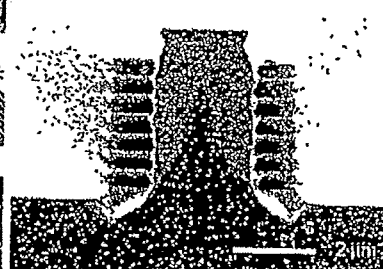


FIG. 20f

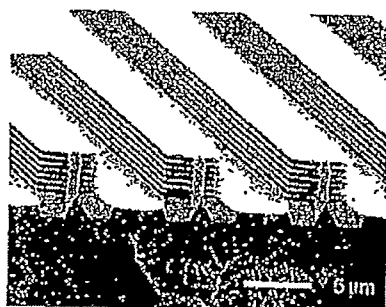


FIG. 20g

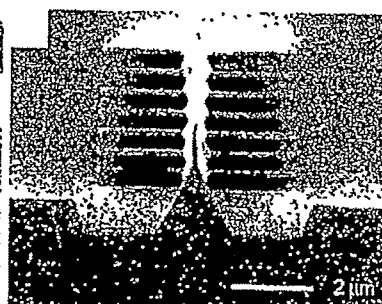


FIG. 20h

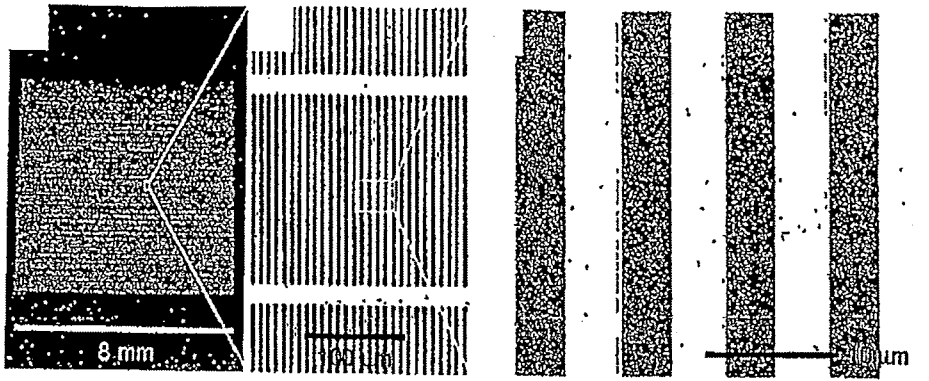


FIG. 21a FIG. 21b

FIG. 21c

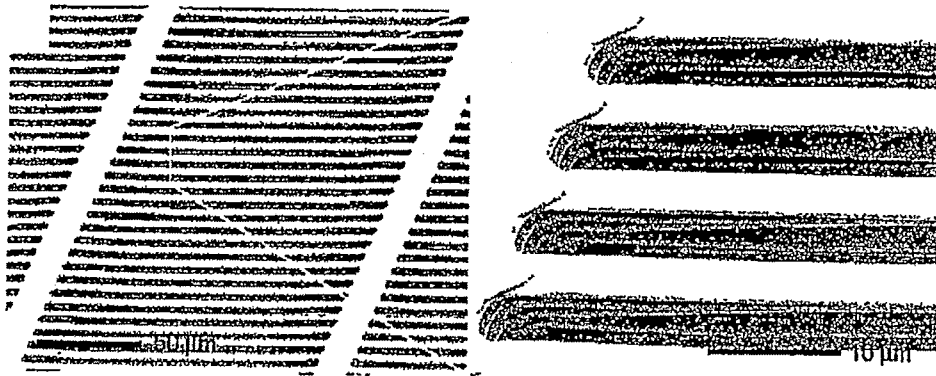


FIG. 21d

FIG. 21e

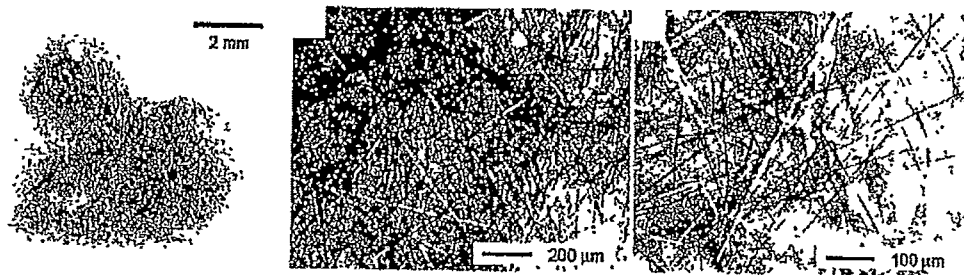


FIG. 22a

FIG. 22b

FIG. 22c

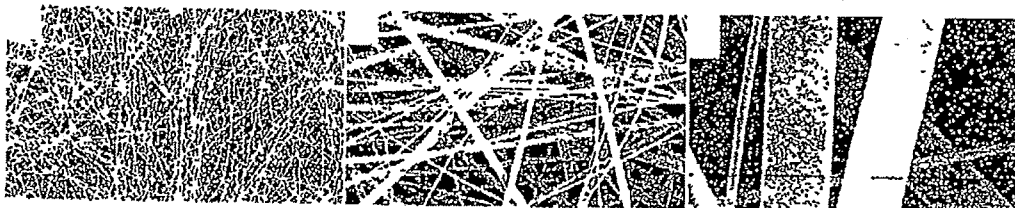


FIG. 22d

FIG. 22e

FIG. 22f

FIG. 23a

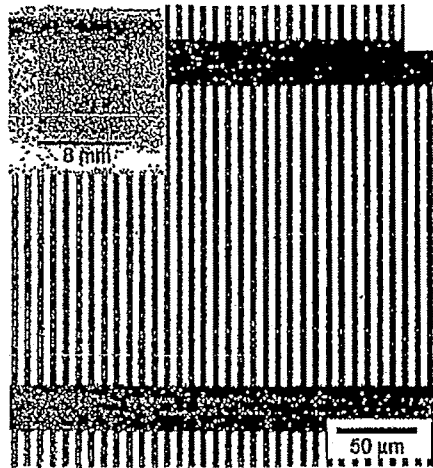


FIG. 23b

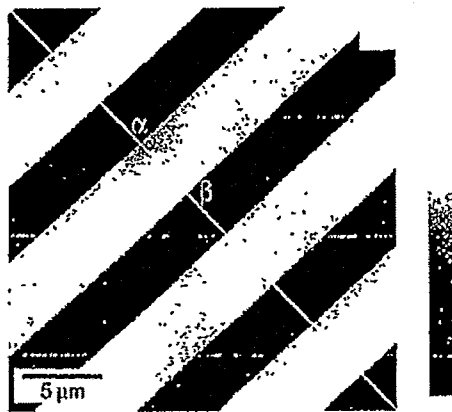


FIG. 23c

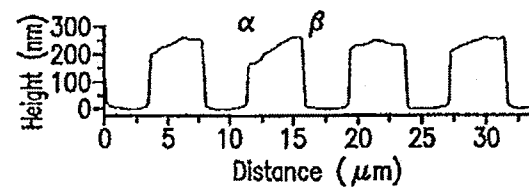


FIG. 23d

